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April 2012

FSUSB20 — Low-Power, 1-Port, High-Speed USB (480Mbps) Switch

Features

-30dB Off Isolation: 250MHz

-30dB Non-adjacent Channel Crosstalk: 250MHz

On Resistance: 4.5Ω Typical (Ron)

-3dB Bandwidth: >720MHz

■ Low-Power Consumption: 1µA Maximum

Control Input: LVTTL Compatible

Bi-Directional Operation

 USB High-Speed and Full-Speed Signaling Capability

Applications

 Cell Phones, PDAs, Digital Cameras, Notebook Computers

Description

FSUSB20 is a low-power, high-bandwidth switch specially designed for switching high-speed USB 2.0 signals in handset and consumer applications; such as cell phone, digital camera, and notebook with hubs or controllers of limited USB I/O. The wide bandwidth (>720MHz) allows signals to pass with minimum edge and phase distortion. Superior channel-to-channel crosstalk results in minimal interference. It is compatible with the high-speed USB 2.0 standard.

Ordering Information

Part Number	Operating Temperature Package Range		Packing Method
FSUSB20L10X	-40 to +85°C	10-Lead MicroPak™, 1.6 x 2.1mm	Tape and Reel
FSUSB20BQX	-40 to +85°C	14-Terminal Depopulation Quad Very-Thin Flat Pack No Lead (DQFN), JEDEC MO-241, 2.5 X 3.0mm	Tube
FSUSB20MUX	-40 to +85°C	10-Lead Molded Small Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide	Tape and Reel

Connection Diagrams

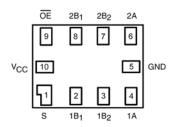


Figure 1. MicroPak™ (Top View)

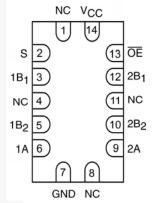


Figure 3. DQFN (Top Through View)

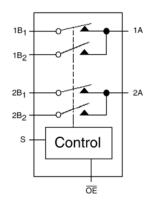


Figure 2. Analog Symbol

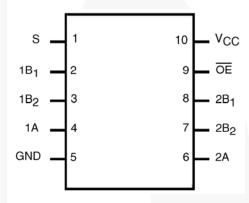


Figure 4. MSOP (Top Through View)

Pin Descriptions

Pin # MicroPak™ / MSOP	Pin # DQFN Pin Names Descr		Description
1	2	S	Select Input
2, 3, 7, 8	3, 5, 10, 12	1B ₁ , 1B ₂ , 2B ₂ , 2B ₁	Bus B
5	7	GND	Ground
4, 6	6, 9	6, 9 1A, 2A Bus A	
9 12		OE	Bus Switch Enable
10 14 V _{CC}		Supply Voltage	

Truth Table

S	OE	Function
Don't Care	HIGH	Disconnect
LOW	LOW	A=B ₁
HIGH	LOW	A=B ₂

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit	
V _{CC}	Supply Voltage		-0.5	4.6	V
Vs	DC Switch Voltage	-0.5	V _{CC} + 0.05	V	
V _{IN}	DC Input Voltage ⁽¹⁾	-0.5	4.6	V	
I _{IK}	DC Input Diode Current, V _{IN} <0V	-50		mA	
I _{OUT}	DC Output Sink Current	50		mA	
I _{CC} / I _{GND}	DC V _{CC} / GND Current	±100		mA	
T _{STG}	Storage Temperature Range	-65	+150	°C	
ESD	Liveran Bady Madal, JECD22 A444	All Pins	7000		V
ESD	Human Body Model, JESD22-A114	I/O to GND	7000		V

Note:

 The input and output negative voltage ratings may be exceeded if the input and output diode current ratings are observed.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Para	Min.	Max.	Unit	
V _{cc}	Power Supply Operating		3.0	3.6	V
V_{IN}	Input Voltage		0	V _{CC}	V
V _{OUT}	Output Voltage		0	V _{CC}	V
	Input Disc and Fall Time	Switch Control Input ⁽²⁾	0	5	ns/V
t_r, t_f	Input Rise and Fall Time Switch I/O		0	DC	ns/v
T _A	Operating Temperature, Free Air		-40	+85	°C

Note:

2. Unused control inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Typical values are at V_{CC} = 3.0V and T_A = 25°C.

Symbol	Doromotor	Condition	V 00	T _A =-40 to +85°C			I Inia
Symbol	Parameter Condition		V _{cc} (V)	Min.	Тур.	Max.	Unit
V _{IK}	Clamp Diode Voltage	I _{IN} = -18mA	3.0			-1.2	V
V _{IH}	High-Level Input Voltage		3.0 to 3.6	2.0			V
V_{IL}	Low-Level Input Voltage		3.0 to 3.6			0.8	V
I _{IN}	Input Leakage Current	$0 \le V_{IN} \le 3.6V$	3.6			±1.0	μA
I _{OFF}	Off-State Leakage Current	$0 \le A, B \le V_{CC}$	3.6			±1.0	μA
	Outitals On Designation (3)	$V_{IN} = 0.8V, I_{ON} = 8mA$	3.0		5	7	
R _{ON}	Switch On Resistance ⁽³⁾	$V_{IN} = 3.0V, I_{ON} = 8mA$	3.0		4.5	6.5	Ω
ΔR_{ON}	Delta R _{ON}	$V_{IN} = 0.8V, V_{IN} = 0V - 1.5V, I_{ON} = 8mA$	3.0		0.3		Ω
R _{FLAT(ON)}	On Resistance Flatness ⁽⁴⁾	I _{OUT} = 8mA	3.0		1		Ω
I _{cc}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND, $I_{OUT} = 0$	3.6			1	μΑ

Notes:

- 3. Measured by the voltage drop between the A and B pins at the indicated current through the switch. On resistance is determined by the lower of the voltages on the A or B pins.
- 4. Flatness is defines as the difference between the maximum and the minimum value on resistance over the specified range of conditions.

AC Electrical Characteristics

Typical values are at V_{CC} = 3.3V and T_{A} = 25°C.

Symbol	Parameter	Condition	V _{cc} (V)	Тур.	Max.	Unit	Figure
t _{ON}	Turn-On Time S-to-Bus B	V _B = 0.8V	3.0 to 3.6	4.8	7.0	ns	Figure 9 Figure 10
t _{OFF}	Turn-Off Time S-to-Bus B	V _B = 0.8V	3.0 to 3.6	2.2	4.0	ns	Figure 9 Figure 10
t _{PD}	Propagation Delay	C _L = 10pF	3.0 to 3.6	0.25		ns	Figure 14
O _{IRR}	Non-Adjacent Off Isolation	$f = 250MHz$, $R_L = 50\Omega$	3.0 to 3.6	-26		dB	Figure 11
X _{TALK}	Non-Adjacent Channel Crosstalk	$f = 250MHz,$ $R_L = 50\Omega$	3.0 to 3.6	-45		dB	Figure 12
BW	-3dB Bandwidth	$R_L = 50\Omega$, $C_L = 0pF$	3.0 to 3.6	750		MHz	Figure 12
		$R_L = 50\Omega$, $C_L = 5pF$		435		IVI□Z	Figure 13

USB Related AC Electrical Characteristics

Typical values are at V_{CC} = 3.3V and T_A = 25°C.

Symbol	Parameter	Condition	V _{cc} (V)	Тур.	Unit	Figure
t _{SK(O)}	Channel-to Channel Skew	C _L = 10pF	3.0 to 3.6	0.051	ns	Figure 14 Figure 16
t _{SK(P)}	Skew of Opposite Transition of the Same Output	C _L = 10pF	3.0 to 3.6	0.020	ns	Figure 14 Figure 16
T _J	Total Jitter	$R_L = 50\Omega, C_L = 10pF$ $t_R = t_F = 750ps$ at 480MPs	3.0 to 3.6	0.170	ns	

Capacitance

Typical values are at V_{CC} = 3.3V and T_{A} = 25°C.

Symbol Parameter		Condition	Тур.	Unit
C _{IN}	Control Pin Input Capacitance	V _{CC} = 0V	2.5	pF
C _{ON}	A/B On Capacitance	V _{CC} = 3.3V, /OE = 0V	12.0	pF
C _{OFF}	Port B Off Capacitance	V _{CC} and /OE = 3.3V	4.5	pF

Performance Characteristics

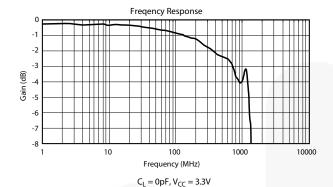


Figure 5. Gain vs. Frequency

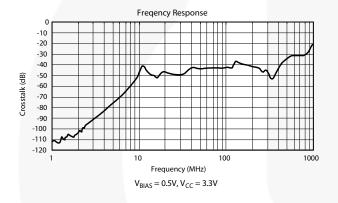


Figure 7. Crosstalk

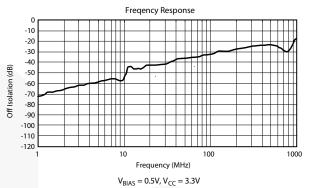


Figure 6. Off Isolation

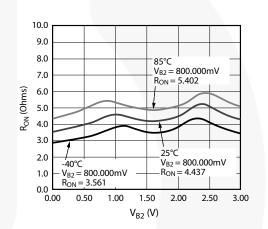
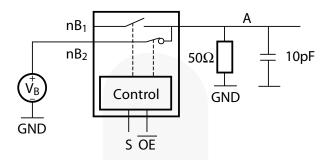


Figure 8. Ron

AC Loadings and Waveforms



Notes: Input driven by 50Ω source terminated in 50Ω . C_L includes load and stray capacitance. Input PRR-1.0MHz, $t_W = 500$ ns.

Figure 9. AC Test Circuit

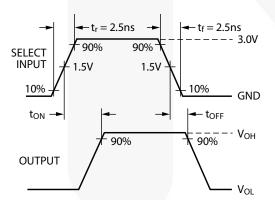


Figure 10. AC Waveforms

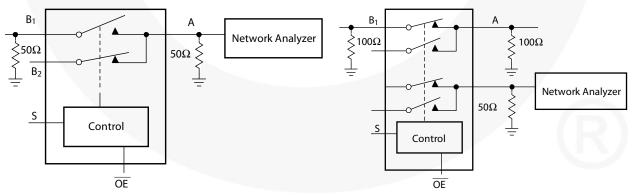


Figure 11. Off Isolation Test

Figure 12. Crosstalk Test

AC Loadings and Waveforms В Network Analyzer 50Ω Control GND OE Figure 13. Bandwidth Test 800mV Input 400mV t_{PHL} t_{PLH} V_{OH} Output V_{OL} Figure 14. Propagation Delay 800mV 50% Input 400mV 0 t_{PHL} $t_{\text{PLH}} \\$ V_{OH} 50% Output V_{OL} $t_{SK(P)} = \left| \; t_{PHL} - t_{PHL} \; \right|$ Figure 15. Pulse Skew t_{SP(P)} 800mV - 50% Input 400mV t_{PHL1} $t_{PLH1} \\$ Output 1 t_{SK(O)} t_{SK(O)} 50% Output 2 $t_{SK(O)} = \left| \ t_{PLH1} - t_{PLH2} \ \right| \ or \ \left| \ t_{PHL1} - t_{PHL2} \ \right|$ Figure 16. Output Skew t_{SK(O)}

Physical Dimensions

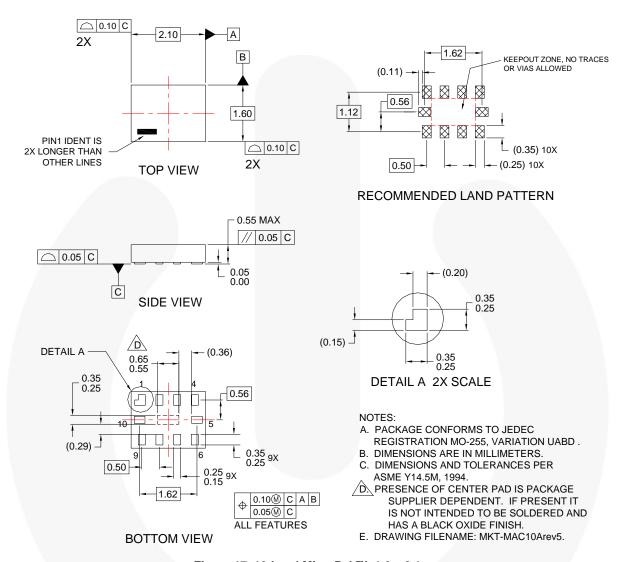


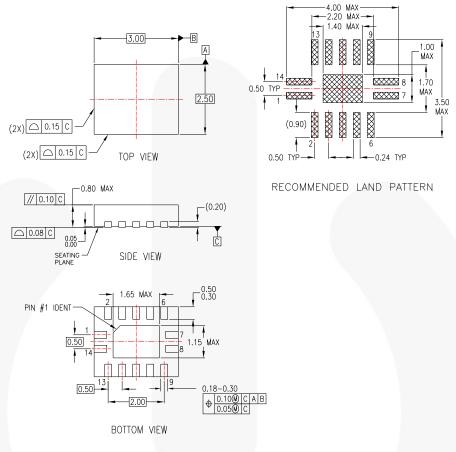
Figure 17. 10-Lead MicroPak™, 1.6 x 2.1mm

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Physical Dimensions



NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-241, VARIATION AA
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

MLP14ArevA

Figure 18. 14-Terminal Depopulation Quad Very-Thin Flat Pack No Lead (DQFN), JEDEC MO-241, 2.5 X 3.0mm

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Physical Dimensions Α 3.00±0.10 В (0.30 2.45 4.90 3.00±0.10 PIN#1 ID QUADRANT (0.381) TOP VIEW 0.85±0.10 1.10 MAX Ċ **END VIEW** ○ 0.10 C ALL LEAD TIPS 12° TOP & BOTTOM □.08 M A B C SIDE VIEW GAUGE PLANE R0.13 TYP SEATING NOTES: UNLESS OTHERWISE SPECIFIED 0.22 0.40 THIS PACKAGE CONFORMS TO JEDEC MO-187 VARIATION BA. ALL DIMENSIONS ARE IN MILLIMETERS. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS. DIMENSIONS AND TOLERANCES AS PER ASME (0.95) **DETAIL** A SCALE 20:1 /14.5-1994 LAND PATTERN AS PER IPC7351#SOP50P490X110-10AN F. FILE NAME: MKT-MUA10AREV3

Figure 19. 10-Lead Molded Small Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide

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